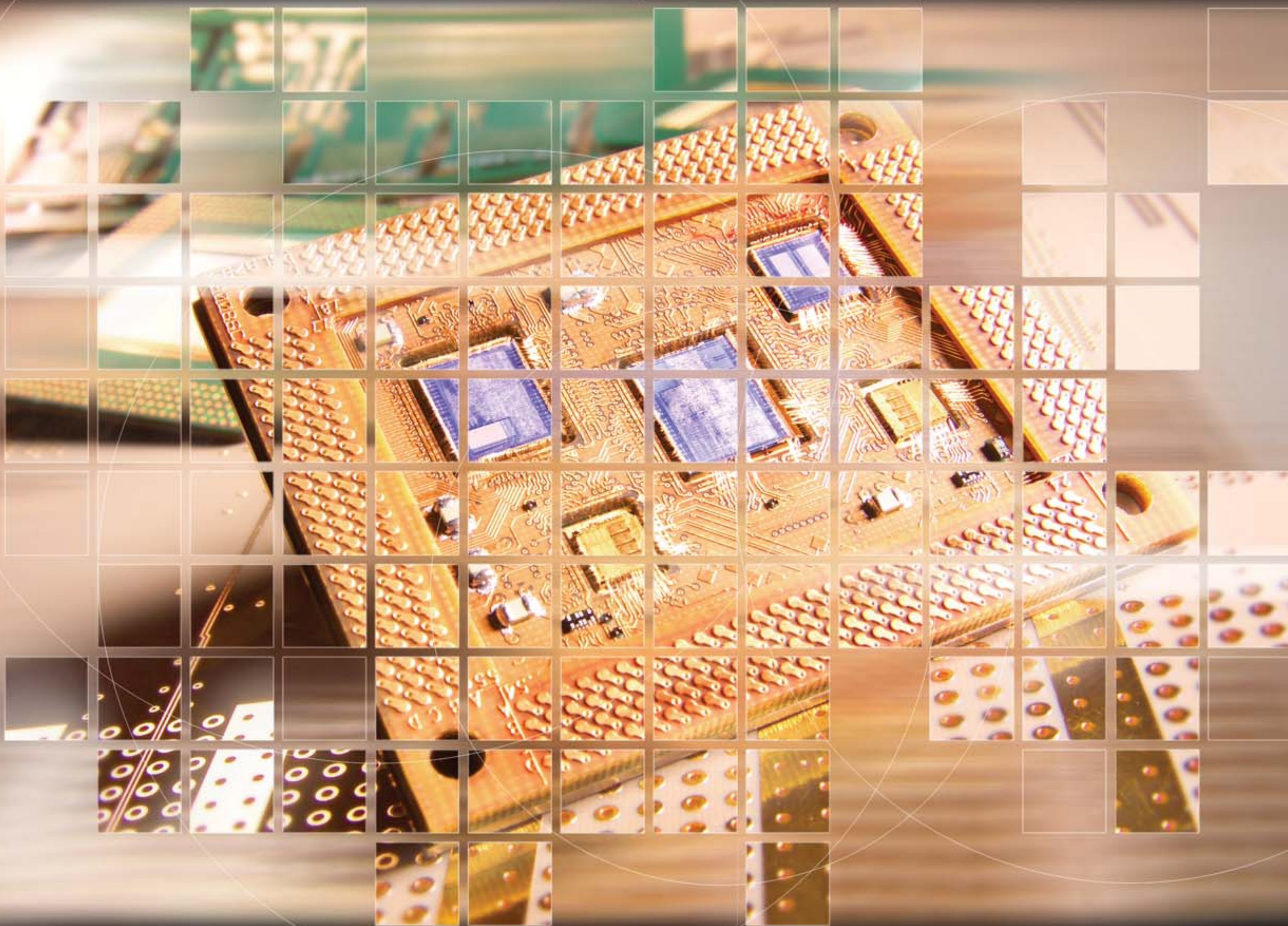
CHIP CARRIERS & MULTI-CHIP MODULES

HDI • MULTI-TIERED CAVITY • MCM-L



Maintaining the highest standards in design and manufacture of high-density, highly complex carriers and modules.

compunetics

excellence, measured in microns.

Compunetics excels in customized products and prototypes that can be produced in small runs with fast turnaround.

These products can combine many of these valuable features:

- High density
- Buried resistors
- Multi-tiered cavity
- Edge plating
- 2 mil (50 µm) trace/space
- Heat spreader
- Aluminum wedge or gold ball wirebond surface
- Flip chip
- Low-to-moderate volume
- Quick turnaround

Applications include:

- Digital imaging, including real-time x-ray
- Global Positioning Satellite (GPS) Systems
- Handheld applications
- Custom chip packaging
- Military, including: Smart Weapons & Undersea Ordinates
- IC Testing
- High speed computing
- Fiber optic networks

CHIP CARRIERS

High density packaging for the most complex die.

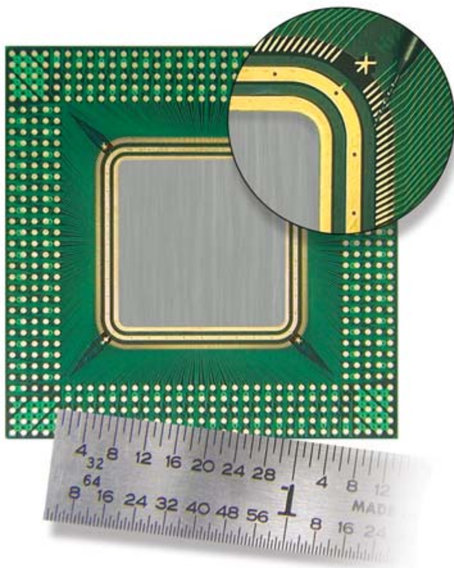
Specifications

Layers: 4

Trace/Space: 3/2 (75/50 µm)

Finish: Electrolytic Ni/Au
Bonded Heat Spreader
Edge Plating
Blind Microvias

Material: High Tg FR4



MCM — MULTICHIP MODULES

Highly functional and reliable solutions to your MCM needs.

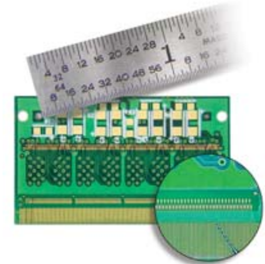
Digital Imaging

Layers: 4

Material: High Tg FR4

Trace Width: 0.0015 +/-0.0003”

Surface Finish: Electrolytic Gold and Nickel



Military

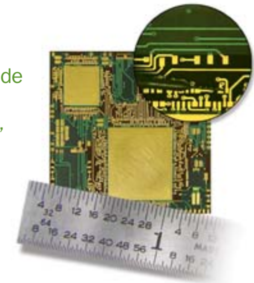
Layers: 8

Material: Thermount/Polyimide (Arlon 85N)

Trace Width: 0.002 +/- 0.0003”

Stacked Microvias: L1 to L2 to L3; L8 to L7 to L6

Surface Finish: Electrolytic Gold and Nickel



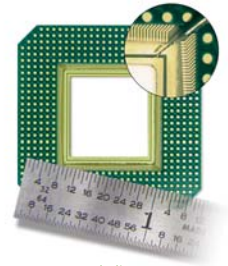
Supercomputing

Layers: 8

Material: High Tg FR4

Trace Width: 0.002 +/- 0.0003”
Controlled Impedance (75 Ohms +/- 10%)
Two Tiered Cavity Design
Edge Plating
406 Buried Resistors (65ohms +/- 15%; Ohmega material)

Surface Finish: Electrolytic Gold and Nickel



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